



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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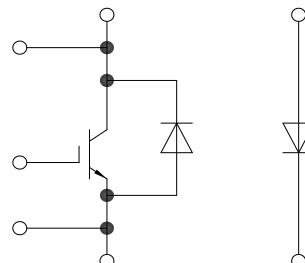
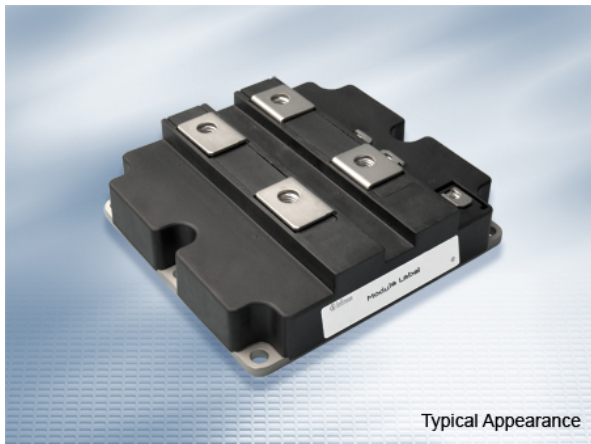
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IHM-B Modul mit Chopper Konfiguration  
IHM-B module with chopper configuration



$V_{CES} = 1700V$   
 $I_{C\ nom} = 800A / I_{CRM} = 1600A$

**Typische Anwendungen**

- Chopper-Anwendungen
- Hochleistungsumrichter
- Traktionsumrichter
- Windgeneratoren

**Typical Applications**

- Chopper applications
- High power converters
- Traction drives
- Wind turbines

**Elektrische Eigenschaften**

- Erweiterte Sperrschichttemperatur  $T_{vj\ op}$
- Niedriges  $V_{CEsat}$

**Electrical Features**

- Extended operating temperature  $T_{vj\ op}$
- Low  $V_{CEsat}$

**Mechanische Eigenschaften**

- 4 kV AC 1min Isolationsfestigkeit
- AlSiC Bodenplatte für erhöhte thermische Lastwechselfestigkeit
- Gehäuse mit CTI > 400
- Große Luft- und Kriechstrecken
- Hohe Last- und thermische Wechselfestigkeit
- Hohe Leistungsdichte
- IHM B Gehäuse

**Mechanical Features**

- 4 kV AC 1min insulation
- AlSiC base plate for increased thermal cycling capability
- Package with CTI > 400
- High creepage and clearance distances
- High power and thermal cycling capability
- High power density
- IHM B housing

**Module Label Code**

Barcode Code 128



DMX - Code



**Content of the Code**

Content of the Code	Digit
Module Serial Number	1 - 5
Module Material Number	6 - 11
Production Order Number	12 - 19
Datecode (Production Year)	20 - 21
Datecode (Production Week)	22 - 23

prepared by: WB	date of publication: 2016-01-21	
approved by: IB	revision: V3.1	UL approved (E83335)



**IGBT, Brems-Chopper / IGBT, Brake-Chopper**  
**Höchstzulässige Werte / Maximum Rated Values**

Kollektor-Emitter-Sperrspannung Collector-emitter voltage	$T_{vj} = -40^{\circ}\text{C}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CES}$	1570 1700 1700	V
Kollektor-Dauergleichstrom Continuous DC collector current	$T_C = 100^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$	$I_{C\text{nom}}$	800	A
Periodischer Kollektor-Spitzenstrom Repetitive peak collector current	$t_P = 1\text{ ms}$	$I_{CRM}$	1600	A
Gesamt-Verlustleistung Total power dissipation	$T_C = 25^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$	$P_{\text{tot}}$	5,20	kW
Gate-Emitter-Spitzenspannung Gate-emitter peak voltage		$V_{GES}$	+/-20	V

**Charakteristische Werte / Characteristic Values**

			min.	typ.	max.	
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage	$I_C = 800\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 800\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 800\text{ A}, V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\text{sat}}$	1,90 2,30 2,40	2,25	V V V
Gate-Schwellenspannung Gate threshold voltage	$I_C = 48,0\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$		$V_{GEth}$	5,20	5,80	6,40 V
Gateladung Gate charge	$V_{GE} = -15\text{ V} \dots +15\text{ V}$		$Q_G$	8,50		$\mu\text{C}$
Interner Gatewiderstand Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		$R_{Gint}$	1,9		$\Omega$
Eingangskapazität Input capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		$C_{ies}$	65,0		nF
Rückwirkungskapazität Reverse transfer capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		$C_{res}$	2,10		nF
Kollektor-Emitter-Reststrom Collector-emitter cut-off current	$V_{CE} = 1570\text{ V}, V_{GE} = 0\text{ V}, T_{vj} = 25^{\circ}\text{C}$		$I_{CES}$		5,0	mA
Gate-Emitter-Reststrom Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$		$I_{GES}$		400	nA
Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load	$I_C = 800\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 0,39\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{don}$	0,50 0,55 0,55		$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Anstiegszeit, induktive Last Rise time, inductive load	$I_C = 800\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 0,39\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_r$	0,10 0,12 0,12		$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load	$I_C = 800\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 2,2\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{doff}$	1,10 1,20 1,25		$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Fallzeit, induktive Last Fall time, inductive load	$I_C = 800\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 2,2\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_f$	0,40 0,70 0,75		$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Einschaltverlustenergie pro Puls Turn-on energy loss per pulse	$I_C = 800\text{ A}, V_{CE} = 900\text{ V}, L_S = 50\text{ nH}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 0,39\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{on}$	180 245 265		mJ mJ mJ
Abschaltverlustenergie pro Puls Turn-off energy loss per pulse	$I_C = 800\text{ A}, V_{CE} = 900\text{ V}, L_S = 50\text{ nH}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 2,2\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{off}$	240 325 345		mJ mJ mJ
Kurzschlußverhalten SC data	$V_{GE} \leq 15\text{ V}, V_{CC} = 1000\text{ V}$ $V_{CE\max} = V_{CES} - L_{sCE} \cdot di/dt$ $t_P \leq 10\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$		$I_{SC}$	3800		A
Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case	pro IGBT / per IGBT		$R_{thJC}$		23,2	K/kW
Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink	pro IGBT / per IGBT $\lambda_{\text{Paste}} = 1\text{ W/(m}\cdot\text{K)} / \lambda_{\text{grease}} = 1\text{ W/(m}\cdot\text{K)}$		$R_{thCH}$	30,0		K/kW
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{op}}$	-40	150	$^{\circ}\text{C}$

prepared by: WB	date of publication: 2016-01-21
approved by: IB	revision: V3.1



**Diode, Brems-Chopper / Diode, Brake-Chopper**  
**Höchstzulässige Werte / Maximum Rated Values**

Periodische Spitzensperrspannung Repetitive peak reverse voltage	$T_{vj} = -40^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{RRM}$	1570 1700 1700	V
Dauergleichstrom Continuous DC forward current		$I_F$	800	A
Periodischer Spitzenstrom Repetitive peak forward current	$t_P = 1 \text{ ms}$	$I_{FRM}$	1600	A
Grenzlastintegral $I^2t$ - value	$V_R = 0 \text{ V}, t_P = 10 \text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0 \text{ V}, t_P = 10 \text{ ms}, T_{vj} = 150^{\circ}\text{C}$	$I^2t$	160 150	kA <sup>2</sup> s kA <sup>2</sup> s
Spitzenverlustleistung Maximum power dissipation	$T_{vj} = 125^{\circ}\text{C}$	$P_{RQM}$	1200	kW
Mindesteinschaltdauer Minimum turn-on time		$t_{on \text{ min}}$	10,0	$\mu\text{s}$

**Charakteristische Werte / Characteristic Values**

			min.	typ.	max.	
Durchlassspannung Forward voltage	$I_F = 800 \text{ A}, V_{GE} = 0 \text{ V}$ $I_F = 800 \text{ A}, V_{GE} = 0 \text{ V}$ $I_F = 800 \text{ A}, V_{GE} = 0 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_F$	1,65 1,65 1,65	2,10	V V V
Rückstromspitze Peak reverse recovery current	$I_F = 800 \text{ A}, -di_F/dt = 6800 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900 \text{ V}$ $V_{GE} = -15 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$I_{RM}$	990 1150 1200		A A A
Sperrverzögerungsladung Recovered charge	$I_F = 800 \text{ A}, -di_F/dt = 6800 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900 \text{ V}$ $V_{GE} = -15 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$Q_r$	220 390 440		$\mu\text{C}$ $\mu\text{C}$ $\mu\text{C}$
Abschaltenergie pro Puls Reverse recovery energy	$I_F = 800 \text{ A}, -di_F/dt = 6800 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900 \text{ V}$ $V_{GE} = -15 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{rec}$	115 235 265		mJ mJ mJ
Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case	pro Diode / per diode		$R_{thJC}$		31,9	K/kW
Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink	pro Diode / per diode $\lambda_{\text{Paste}} = 1 \text{ W}/(\text{m}\cdot\text{K}) / \lambda_{\text{grease}} = 1 \text{ W}/(\text{m}\cdot\text{K})$		$R_{thCH}$	33,0		K/kW
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj \text{ op}}$	-40	150	$^{\circ}\text{C}$

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**Diode, Revers / Diode, Reverse**

**Höchstzulässige Werte / Maximum Rated Values**

Periodische Spitzensperrspannung Repetitive peak reverse voltage	$T_{vj} = -40^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{RRM}$	1570 1700 1700	V
Dauergleichstrom Continuous DC forward current		$I_F$	800	A
Periodischer Spitzenstrom Repetitive peak forward current	$t_P = 1 \text{ ms}$	$I_{FRM}$	1600	A
Grenzlastintegral $I^2t$ - value	$V_R = 0 \text{ V}, t_P = 10 \text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0 \text{ V}, t_P = 10 \text{ ms}, T_{vj} = 150^{\circ}\text{C}$	$I^2t$	105 95,0	$\text{kA}^2\text{s}$ $\text{kA}^2\text{s}$
Spitzenverlustleistung Maximum power dissipation	$T_{vj} = 125^{\circ}\text{C}$	$P_{RQM}$	800	kW
Mindesteinschaltdauer Minimum turn-on time		$t_{on \text{ min}}$	10,0	$\mu\text{s}$

**Charakteristische Werte / Characteristic Values**

			min.	typ.	max.	
Durchlassspannung Forward voltage	$I_F = 800 \text{ A}, V_{GE} = 0 \text{ V}$ $I_F = 800 \text{ A}, V_{GE} = 0 \text{ V}$ $I_F = 800 \text{ A}, V_{GE} = 0 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_F$	1,80 1,90 1,95	2,20	V V V
Rückstromspitze Peak reverse recovery current	$I_F = 800 \text{ A}, -di_F/dt = 6500 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$I_{RM}$	900 1000 1050		A A A
Sperrverzögerungsladung Recovered charge	$I_F = 800 \text{ A}, -di_F/dt = 6500 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$Q_r$	190 320 360		$\mu\text{C}$ $\mu\text{C}$ $\mu\text{C}$
Abschaltenergie pro Puls Reverse recovery energy	$I_F = 800 \text{ A}, -di_F/dt = 6500 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 900 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{rec}$	110 200 230		mJ mJ mJ
Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case	pro Diode / per diode		$R_{thJC}$		39,1	K/kW
Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink	pro Diode / per diode $\lambda_{\text{Paste}} = 1 \text{ W}/(\text{m}\cdot\text{K}) / \lambda_{\text{grease}} = 1 \text{ W}/(\text{m}\cdot\text{K})$		$R_{thCH}$	33,0		K/kW
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj \text{ op}}$	-40	150	$^{\circ}\text{C}$

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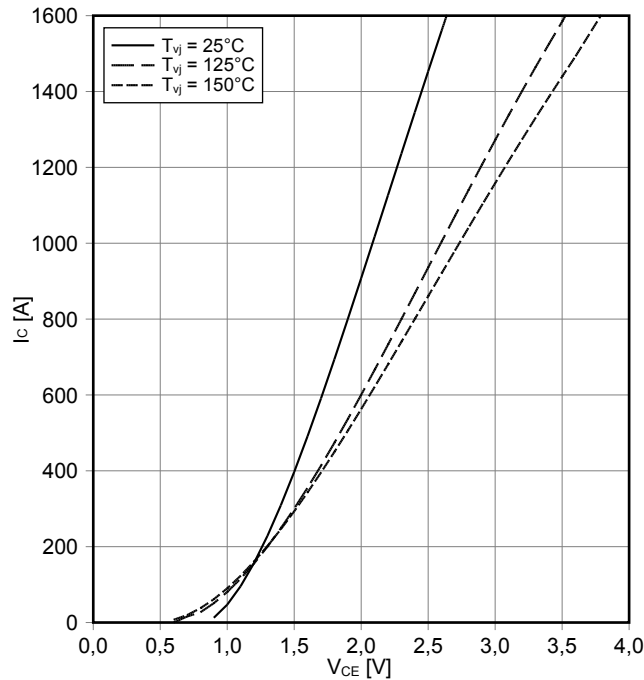
**Modul / Module**

Isolations-Prüfspannung Isolation test voltage	RMS, f = 50 Hz, t = 1 min.	V <sub>ISOL</sub>	4,0		kV
Material Modulgrundplatte Material of module baseplate			AlSiC		
Kriechstrecke Creepage distance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		32,2 32,2		mm
Luftstrecke Clearance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		19,1 19,1		mm
Vergleichszahl der Kriechwegbildung Comperative tracking index		CTI	> 400		
			min.	typ.	max.
Modulstreuintuktivität Stray inductance module		L <sub>SCE</sub>		18	nH
Modulleitungswiderstand, Anschlüsse - Chip Module lead resistance, terminals - chip	T <sub>c</sub> = 25°C, pro Schalter / per switch	R <sub>CC'+EE'</sub> R <sub>AA'+CC'</sub>		0,28 0,25	mΩ
Lagertemperatur Storage temperature		T <sub>stg</sub>	-40		150 °C
Anzugsdrehmoment f. Modulmontage Mounting torque for modul mounting	Schraube M6 - Montage gem. gültiger Applikationsschrift Screw M6 - Mounting according to valid application note	M	4,25		5,75 Nm
Anzugsdrehmoment f. elektr. Anschlüsse Terminal connection torque	Schraube M4 - Montage gem. gültiger Applikationsschrift Screw M4 - Mounting according to valid application note	M	1,8	-	2,1 Nm
	Schraube M8 - Montage gem. gültiger Applikationsschrift Screw M8 - Mounting according to valid application note		8,0	-	10 Nm
Gewicht Weight		G		800	g

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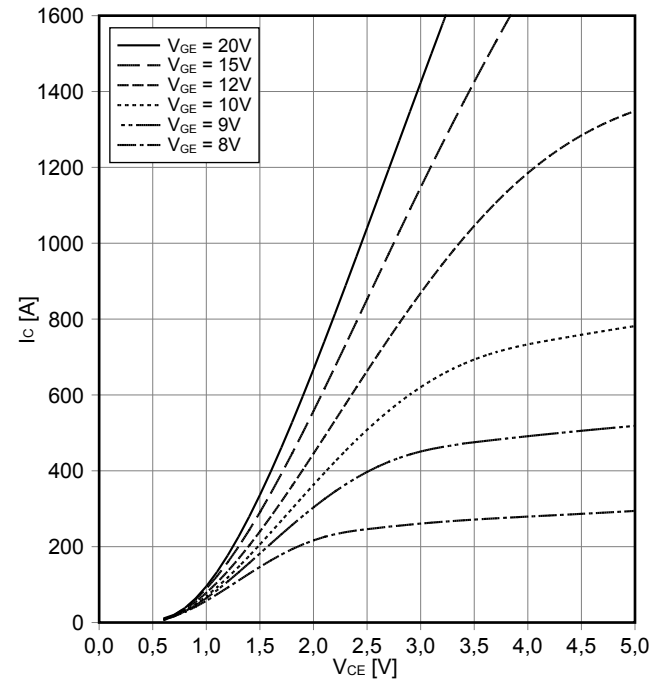
**Ausgangskennlinie IGBT, Brems-Chopper (typisch)**  
**output characteristic IGBT, Brake-Chopper (typical)**

$I_C = f(V_{CE})$   
 $V_{GE} = 15\text{ V}$



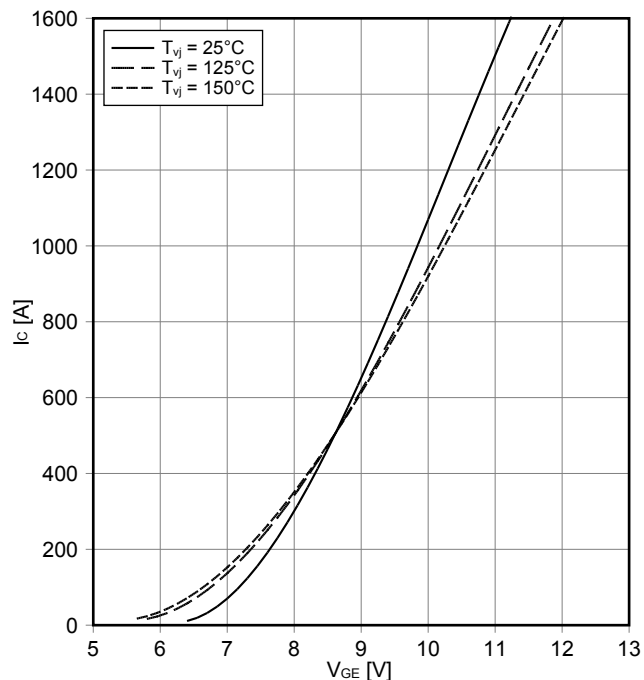
**Ausgangskennlinienfeld IGBT, Brems-Chopper (typisch)**  
**output characteristic IGBT, Brake-Chopper (typical)**

$I_C = f(V_{CE})$   
 $T_{vj} = 150^\circ\text{C}$



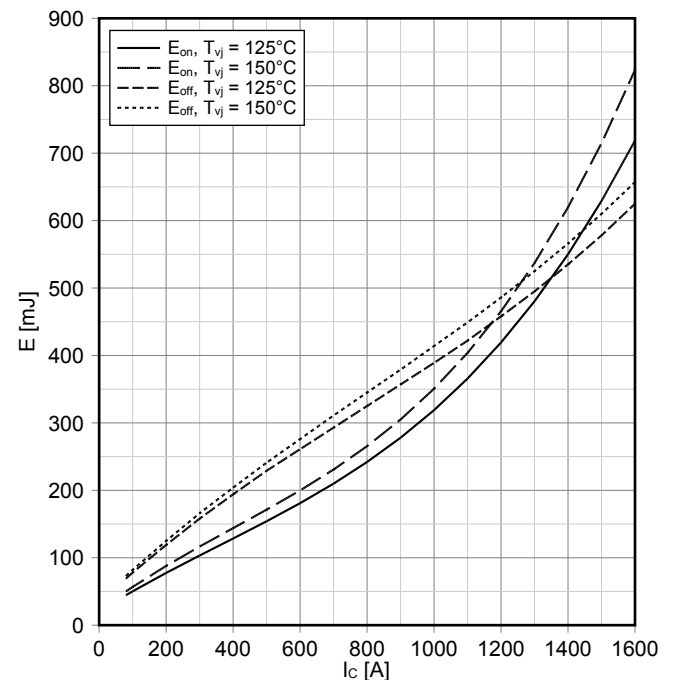
**Übertragungscharakteristik IGBT, Brems-Chopper (typisch)**  
**transfer characteristic IGBT, Brake-Chopper (typical)**

$I_C = f(V_{GE})$   
 $V_{CE} = 20\text{ V}$



**Schaltverluste IGBT, Brems-Chopper (typisch)**  
**switching losses IGBT, Brake-Chopper (typical)**

$E_{on} = f(I_C), E_{off} = f(I_C)$   
 $V_{GE} = \pm 15\text{ V}, R_{Gon} = 0.39\ \Omega, R_{Goff} = 2.2\ \Omega, V_{CE} = 900\text{ V}$

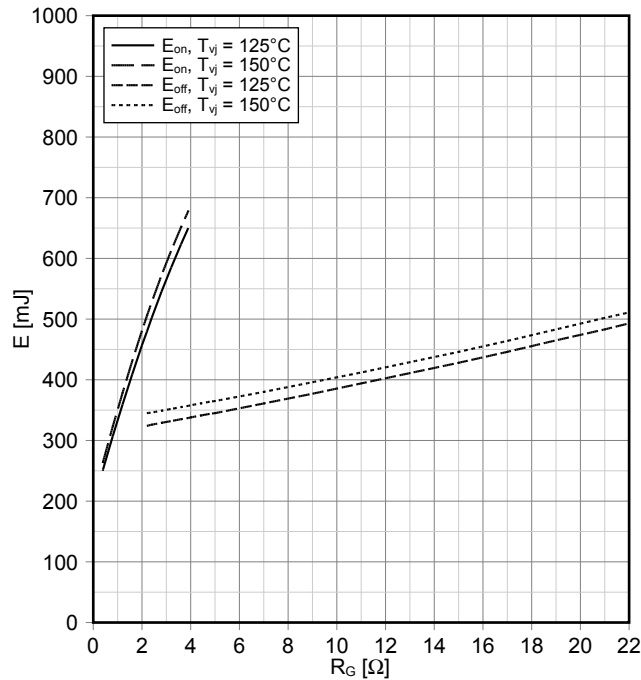


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approved by: IB	revision: V3.1



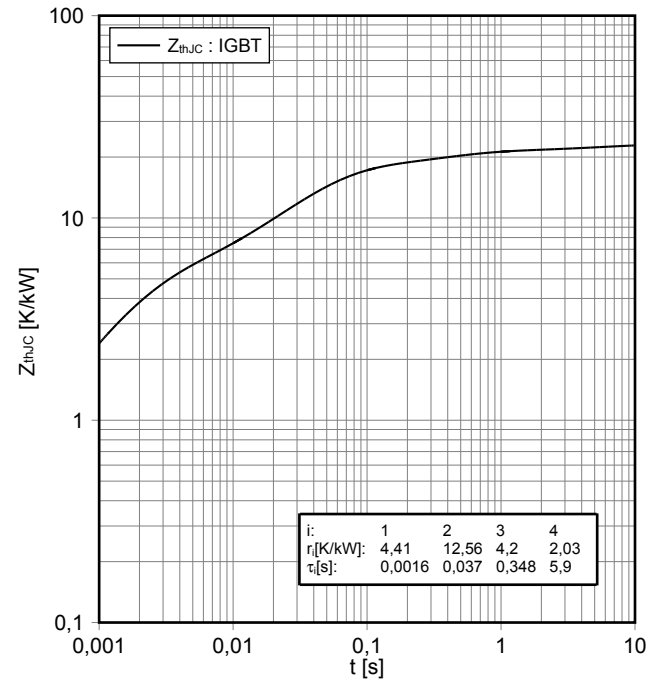
**Schaltverluste IGBT, Brems-Chopper (typisch)**  
**switching losses IGBT, Brake-Chopper (typical)**

$E_{on} = f(R_G), E_{off} = f(R_G)$   
 $V_{GE} = \pm 15\text{ V}, I_C = 800\text{ A}, V_{CE} = 900\text{ V}$



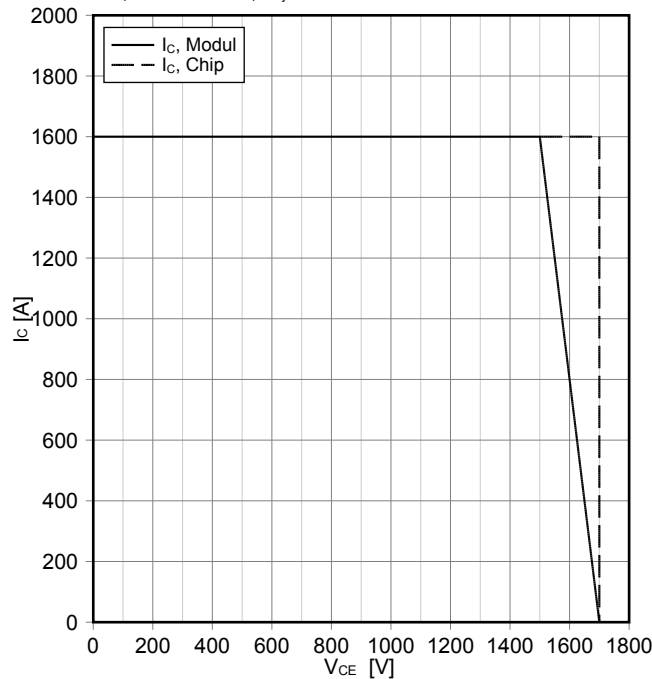
**Transienter Wärmewiderstand IGBT, Brems-Chopper**  
**transient thermal impedance IGBT, Brake-Chopper**

$Z_{thJC} = f(t)$



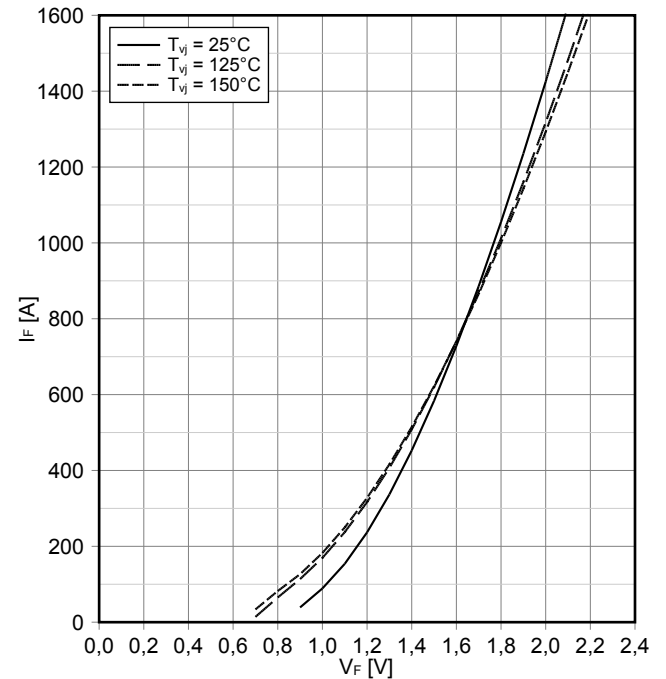
**Sicherer Rückw.-Arbeitsber. IGBT, Brems-Chopper (RBSOA)**  
**reverse bias safe operating area IGBT, Brake-Chopper (RBSOA)**

$I_C = f(V_{CE})$   
 $V_{GE} = \pm 15\text{ V}, R_{Goff} = 2.2\ \Omega, T_{vj} = 150^\circ\text{C}$



**Durchlasskennlinie der Diode, Brems-Chopper (typisch)**  
**forward characteristic of Diode, Brake-Chopper (typical)**

$I_F = f(V_F)$



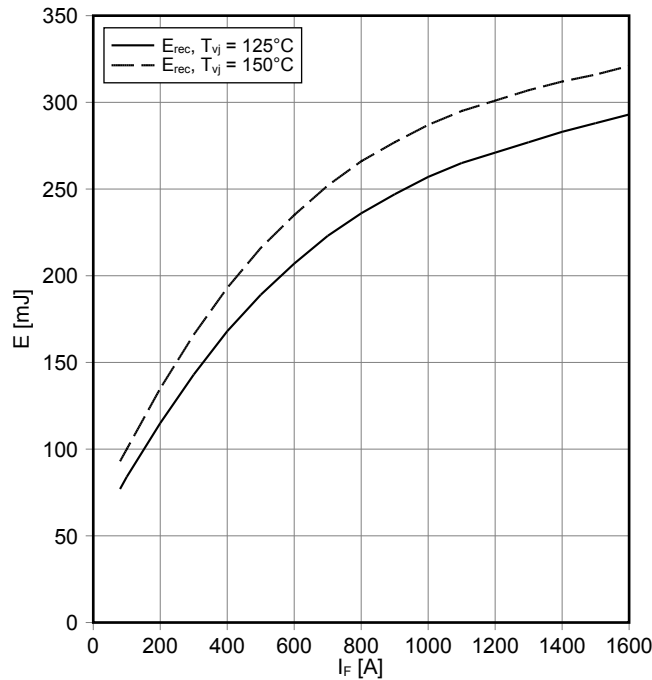
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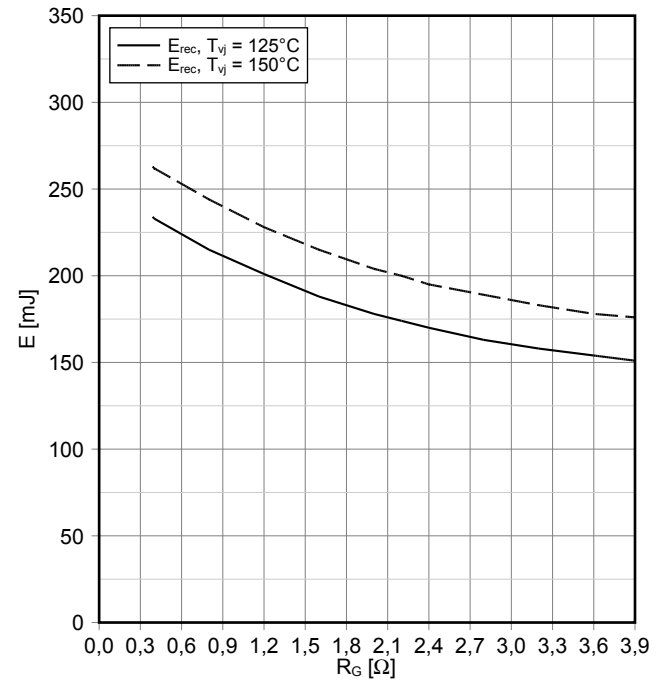
**Schaltverluste Diode, Brems-Chopper (typisch)**  
**switching losses Diode, Brake-Chopper (typical)**

$E_{rec} = f(I_F)$   
 $R_{Gon} = 0.39 \Omega, V_{CE} = 900 V$



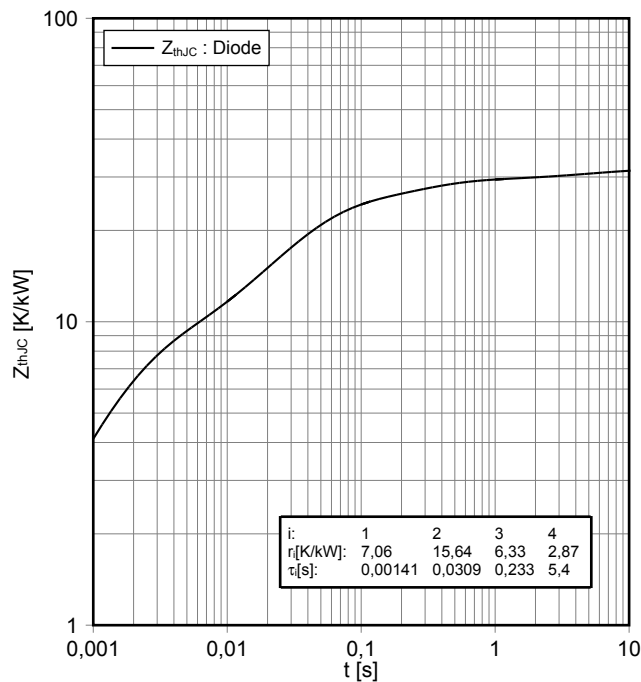
**Schaltverluste Diode, Brems-Chopper (typisch)**  
**switching losses Diode, Brake-Chopper (typical)**

$E_{rec} = f(R_G)$   
 $I_F = 800 A, V_{CE} = 900 V$



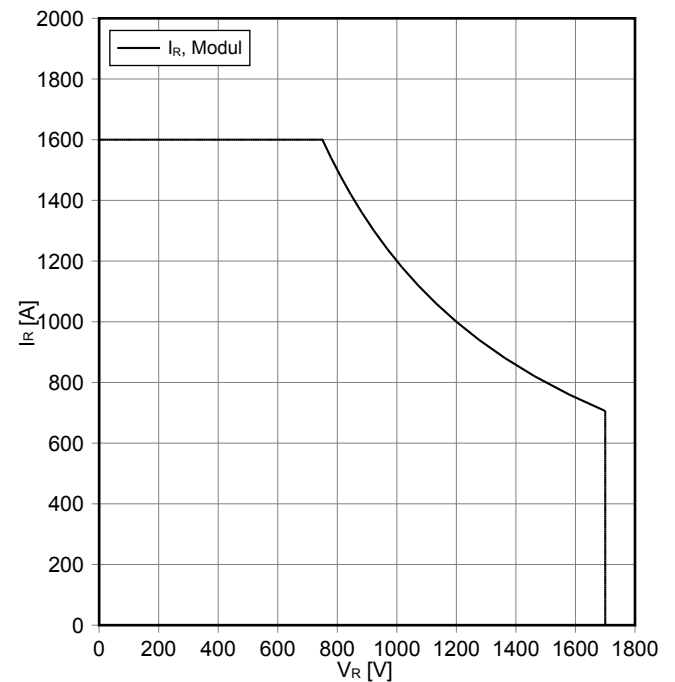
**Transienter Wärmewiderstand Diode, Brems-Chopper**  
**transient thermal impedance Diode, Brake-Chopper**

$Z_{thJC} = f(t)$



**Sicherer Arbeitsbereich Diode, Brems-Chopper (SOA)**  
**safe operation area Diode, Brake-Chopper (SOA)**

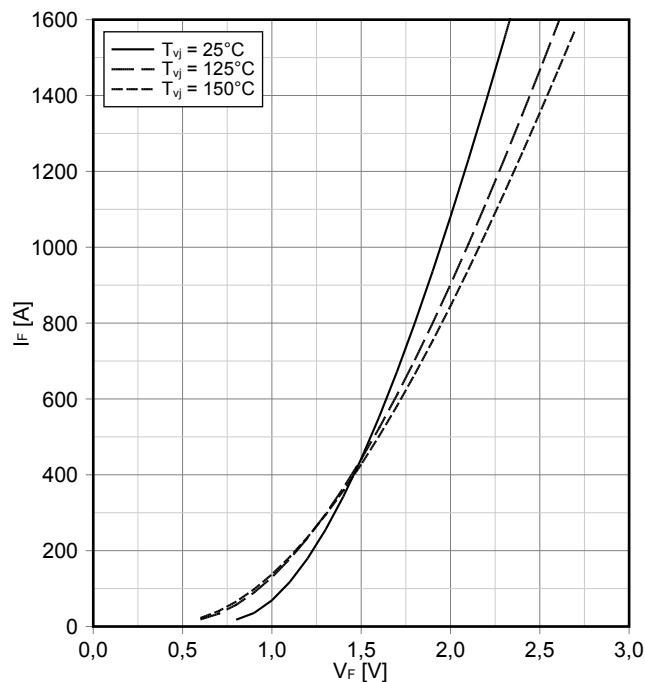
$I_R = f(V_R)$   
 $T_{vj} = 150^\circ C$



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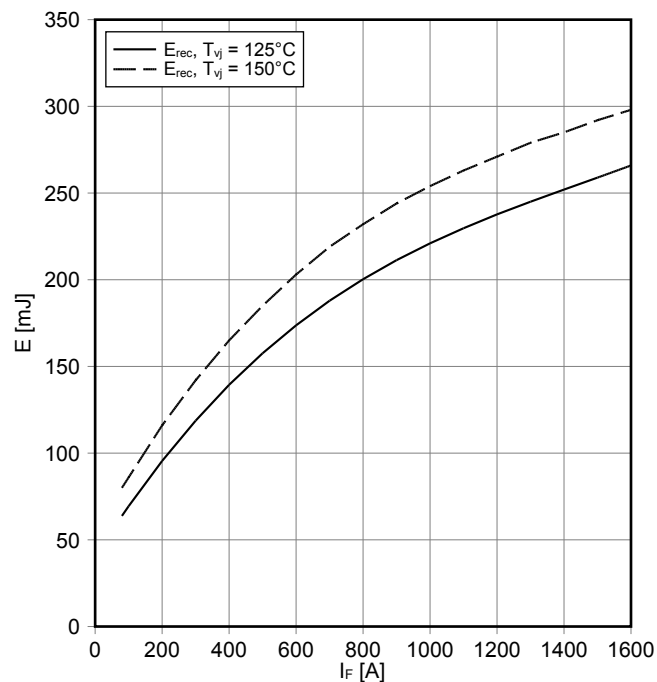


**Durchlasskennlinie der Diode, Revers (typisch)**  
forward characteristic of Diode, Reverse (typical)  
 $I_F = f(V_F)$



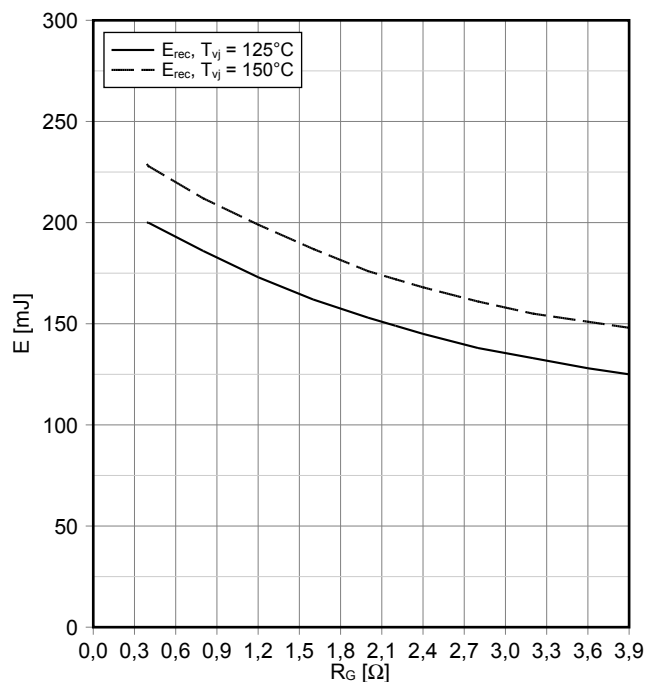
**Schaltverluste Diode, Revers (typisch)**  
switching losses Diode, Reverse (typical)  
 $E_{rec} = f(I_F)$

$R_{Gon} = 0.39 \Omega$ ,  $V_{CE} = 900 V$

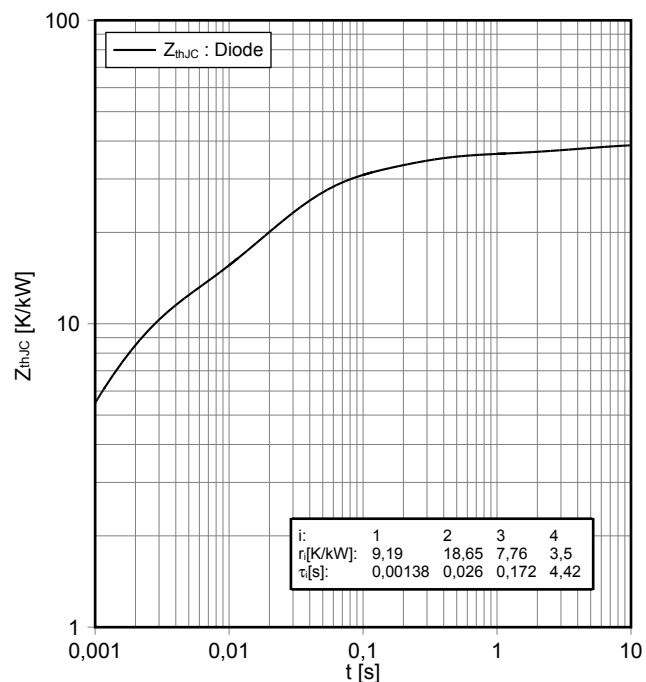


**Schaltverluste Diode, Revers (typisch)**  
switching losses Diode, Reverse (typical)  
 $E_{rec} = f(R_G)$

$I_F = 800 A$ ,  $V_{CE} = 900 V$



**Transienter Wärmewiderstand Diode, Revers**  
transient thermal impedance Diode, Reverse  
 $Z_{thJC} = f(t)$



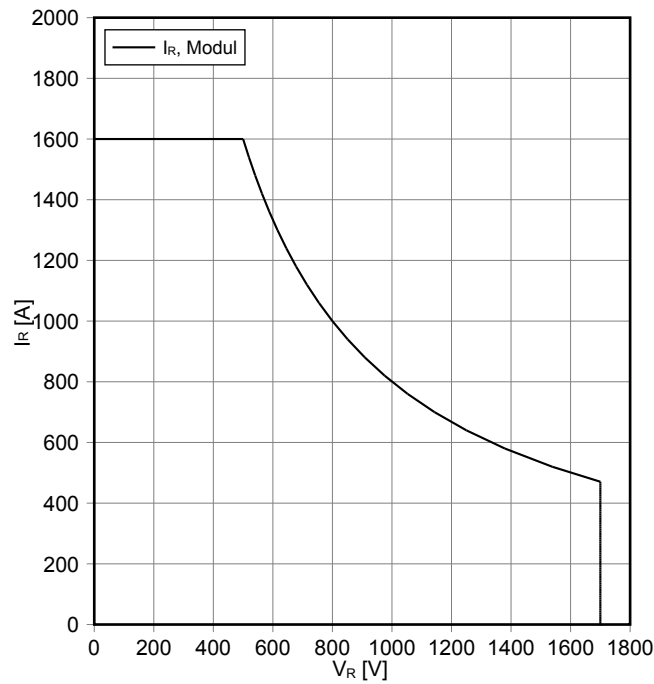
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approved by: IB	revision: V3.1

**Sicherer Arbeitsbereich Diode, Revers (SOA)**

**safe operation area Diode, Reverse (SOA)**

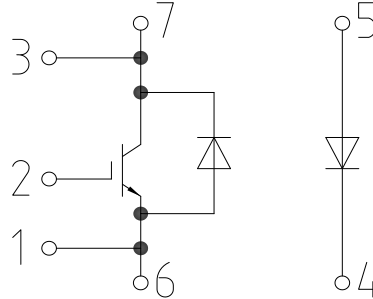
$I_R = f(V_R)$

$T_{vj} = 150^\circ\text{C}$

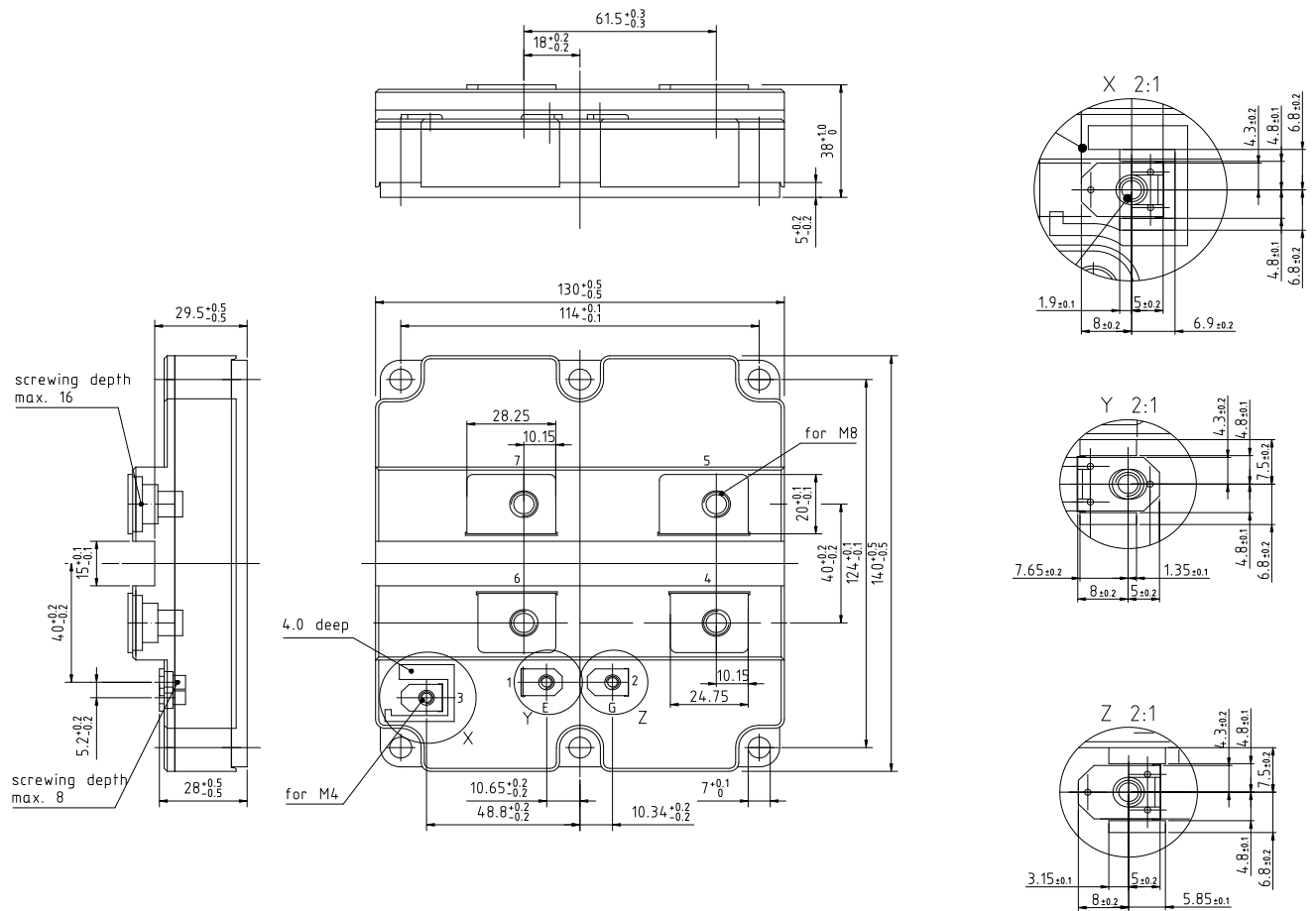


prepared by: WB	date of publication: 2016-01-21
approved by: IB	revision: V3.1

Schaltplan / Circuit diagram



Gehäuseabmessungen / Package outlines



prepared by: WB	date of publication: 2016-01-21
approved by: IB	revision: V3.1



**Published by**  
**Infineon Technologies AG**  
**81726 München, Germany**  
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